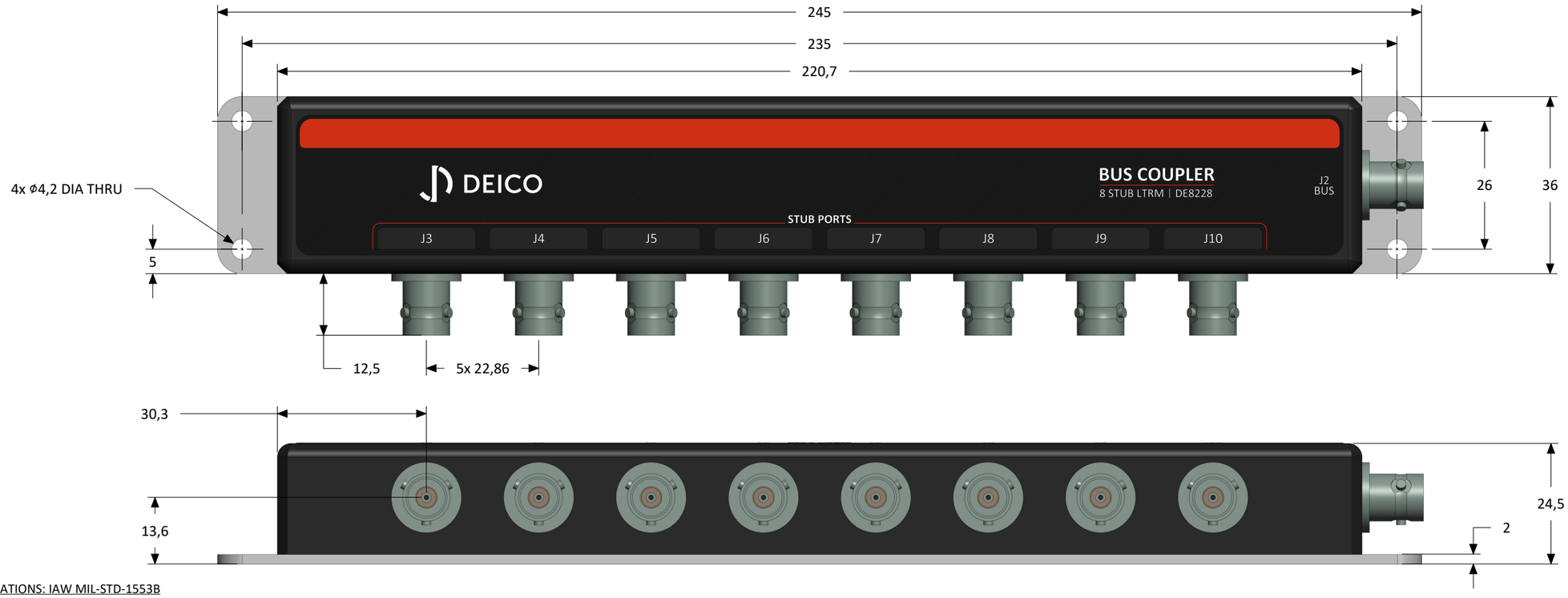


1.0 ELECTRICAL SPECIFICATIONS: IAW MIL-STD-1553B

1.1 COMMON MODE REHECTION: -45.0 Db MAX @ 1.0MHz

1.2 DROOP: 20% MAX (250kHz)

1.3 OVERSHOOT & RINGING: ± 1.0V PEAK (250kHz SQUARE WAVE WITH 100Ns)

1.4 STUB VOLTAGE: 1.0V TO 14.0V P-P; LINE TO LINE; SIGNAL VOLTAGE, TRANSFORMER COUPLING

1.5 INPUT IMPEDANCE OF BUS: 3000 OHMS MIN. (75kHz - 1.0MHz), STUB WITH OPEN CIRCUIT

1.6 CHARACTERISTIC IMPEDANCE: Zo=78 OHMS

1.7 FAULT PROTECTION: 59 OHMS ± 1% 1W (R1-R16) IN SERIES WITH TRANSFORMER WINDING ON BUS SIDE

1.8 TERMINATION RESISTOR VALUE: 78.7 OHMS ± 1% 2W (R17) BUS TERMINATION

2.0 MECHANICAL SPECIFICATIONS:

2.1 ENCLOSURE MATERIAL: AL 5754, 2MM THK.
FINISH: CHEMICAL FILM PER SI-0000-0036, CLASS 2

2.2 MOUNTING PLATE MATERIAL: AL 5754, 2MM THK.
FINISH: CHEMICAL FILM PER SI-0000-0036, CLASS 2

3.0 ENVIRONMENTAL SPECIFICATIONS:

3.1 OPERATING TEMPERATURE RANGE: -55°C TO 125°C

3.2 VIBRATION: MIL-STD-810G_CHG-1 METHOD 514.7 PROCEDURE I

3.3 SHOCK: MIL-STD-810G_CHG-1 METHOD 516.7 PROCEDURE V

3.4 HIGH TEMPERATURE OPERATING: MIL-STD-810G_CHG-1 METHOD 501.6 PROCEDURE II, +125°C

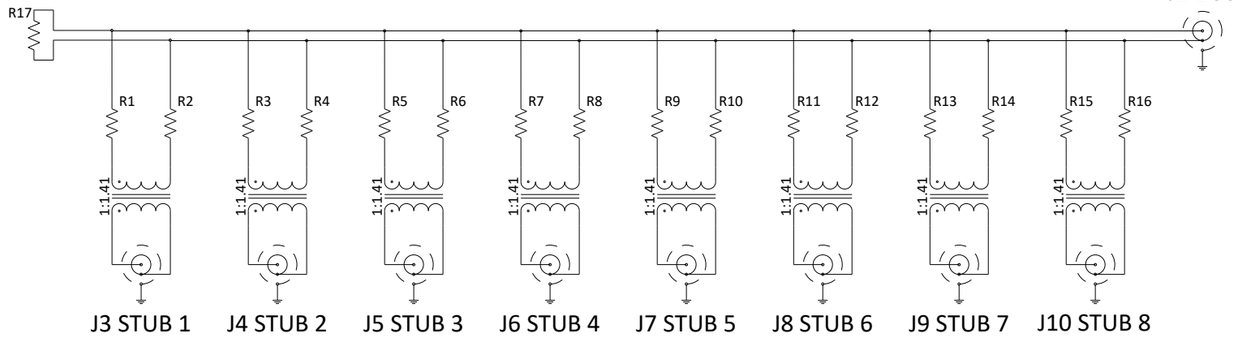
3.5 LOW TEMPERATURE OPERATING: MIL-STD-810G_CHG-1 METHOD 502.6 PROCEDURE II, -55°C

3.6 HIGH TEMPERATURE STORAGE: MIL-STD-810G_CHG-1 METHOD 501.6 PROCEDURE I, +125°C

3.7 LOW TEMPERATURE STORAGE: MIL-STD-810G_CHG-1 METHOD 502.6 PROCEDURE I, -55°C

3.8 RAIN: MIL-STD-810G METHOD 506.5 PROCEDURE I

SCHEMATIC DIAGRAM



INTERMATEABILITY

CONNECTOR	RECOMMENDED MATING CONNECTOR
BJ770	PL75

UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS.

PRODUCT NAME: *BOX TYPE BUS COUPLER 8 STUB LTRM*				DEICO www.deico.com.tr
DOCUMENT NAME: *DE8228 - TECHNICAL DRAWING*				
SIZE: A3	SCALE: 1:1	REVISION: 1	REVISION DATE: 28.11.2023	SHEET: 1/1